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16 VCC

15 TC

14 Q₀

13 🛛 Q1

12 Q2

11 Q3

10 CET

- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- CY54FCT163T
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT163T
 G4 mA Output Sink
 - 64-mA Output Sink Current
 - 32-mA Output Source Current

description

The 'FCT163T devices are high-speed synchronous modulo-16 binary counters. They are synchronously presettable for application in programmable dividers. These devices have two

types of count-enable (CEP and CET) inputs, plus a terminal-count (TC) output for versatility in forming synchronous multistaged counters. The 'FCT163T devices have a synchronous-reset (\overline{SR}) input that overrides counting and parallel loading, and allows the outputs to be reset simultaneously on the rising edge of the clock.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

NAME	DESCRIPTION
CEP	Count-enable parallel input
CET	Count-enable trickle input
CP	Clock pulse input (active rising edge)
SR	Synchronous-reset input (active low)
Р	Parallel data inputs
PE	Parallel-enable input (active low)
Q	Flip-flop outputs
TC	Terminal-count output

PIN DESCRIPTION



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Copyright © 2001, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

GND 8	9] PE
•••••••••	L PACKAGE VIEW)
C CP	

CY74FCT163CT . . . Q OR SO PACKAGE (TOP VIEW)

SR

CP [2

P₁ [4

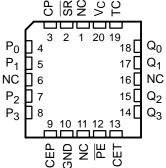
P₀ [

P₂ [5

P₃ [] 6

CEP 17

3



NC - No internal connection

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TA	PAC	KAGE [†]	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QSOP – Q	Tape and reel	5.8	CY74FCT163CTQCT	FT163-3
–40°C to 85°C	SOIC – SO	Tube	5.8	CY74FCT163CTSOC	FCT163C
	3010 - 30	Tape and reel	5.8	CY74FCT163CTSOCT	1011030
–55°C to 125°C	LCC – L	Tube	11.5	CY54FCT163TLMB	

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

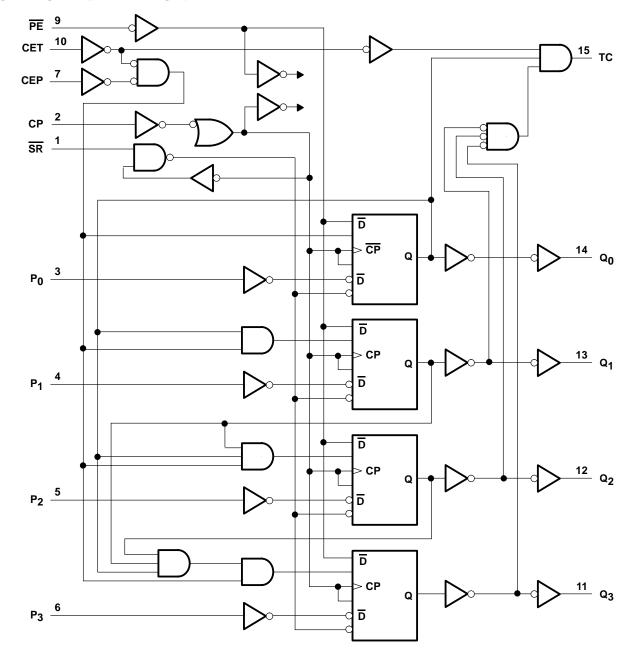
		10140		
	INP	UTS	ACTION ON THE RISING	
SR	PE	CET	CEP	CLOCK EDGE(S)
L	Х	Х	Х	Reset (clear)
н	L	Х	Х	$\text{Load}\;(P_n\toQ_n)$
н	Н	Н	Н	Count (incremental)
н	Н	L	Х	No change (hold)
н	Н	Х	L	No change (hold)

FUNCTION TABLE

H = High logic level, L = Low logic level, X = Don't care



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logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range to ground potential	
DC input voltage range	–0.5 V to 7 V
DC output voltage range	–0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ_{JA} (see Note 1): Q package	
SO package	57°C/W
Ambient temperature range with power applied, T _A	. −65°C to 135°C
Storage temperature range, T _{stg}	. –65°C to 150°C

⁺ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

		CY54FCT163T			CY	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			-12			-32	mA
IOL	Low-level output current			32			64	mA
ТĄ	Operating free-air temperature	-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.



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	TEST CONDITIONS	CY	′54FCT16	3T	CY	UNIT		
PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNIT
Maria	$V_{CC} = 4.5 \text{ V}, \qquad I_{IN} = -18 \text{ mA}$		-0.7	-1.2				V
VIK	$V_{CC} = 4.75 \text{ V}, I_{IN} = -18 \text{ mA}$					-0.7	-1.2	v
	$V_{CC} = 4.5 \text{ V}, \qquad I_{OH} = -12 \text{ mA}$	2.4	3.3					
Vон	$V_{CC} = 4.75 V$ $I_{OH} = -32 mA$				2			V
	$V_{CC} = 4.75 \text{ V}$ $I_{OH} = -15 \text{ mA}$				2.4	3.3		
Ve	$V_{CC} = 4.5 \text{ V}, \qquad I_{OL} = 32 \text{ mA}$		0.3	0.55				V
VOL	$V_{CC} = 4.75 \text{ V}, I_{OL} = 64 \text{ mA}$					0.3	0.55	v
V _{hys}	All inputs		0.2			0.2		V
1.	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = V_{CC}$			5				
l	$V_{CC} = 5.25 \text{ V}, V_{IN} = V_{CC}$						5	μA
I	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$			±1				μA
lΉ	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$						±1	μA
1	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$			±1				μA
١Ľ	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$						±1	μA
t	V _{CC} = 5.5 V, V _{OUT} = 0 V	-60	-120	-225				mA
IOS‡	V _{CC} = 5.25 V, V _{OUT} = 0 V				-60	-120	-225	IIIA
loff	V _{CC} = 0 V, V _{OUT} = 4.5 V			±1			±1	μA
1	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} \le 0.2 \text{ V}, \qquad V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.1	0.2				
ICC	$V_{CC} = 5.25 \text{ V}, V_{IN} \le 0.2 \text{ V}, V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.1	0.2	mA
	$V_{CC} = 5.5 \text{ V}, \text{ V}_{IN} = 3.4 \text{ V}^{\$}, \text{ f}_1 = 0$, Outputs open		0.2	2				mA
∆ICC	$V_{CC} = 5.25 \text{ V}, V_{IN} = 3.4 \text{ V}\$, f_1 = 0$, Outputs open					0.2	2	mA
¶	$\label{eq:VCC} \begin{array}{l} V_{CC} = 5.5 \ \text{V}, \ \text{Load mode}, \ \text{Outputs open}, \\ \text{One bit switching at 50\% duty cycle}, \\ \text{CEP} = \text{CET} = \overrightarrow{\text{PE}} = \text{GND}, \ \overrightarrow{\text{SR}} = \text{V}_{CC}, \\ \text{V}_{IN} \leq 0.2 \ \text{V or } \ \text{V}_{IN} \geq \text{V}_{CC} - 0.2 \ \text{V} \end{array}$		0.06	0.12				mA/
ICCD	$\label{eq:VCC} \begin{array}{l} V_{CC} = 5.25 \ \text{V}, \ \text{Load mode}, \ \text{Outputs open}, \\ \text{One bit switching at 50\% } \underline{duty} \ \text{cycle}, \\ \text{CEP} = \text{CET} = \text{PE} = \text{GND}, \ \text{SR} = \text{V}_{CC}, \\ \text{V}_{IN} \leq 0.2 \ \text{V} \ \text{or} \ \text{V}_{IN} \geq \text{V}_{CC} - 0.2 \ \text{V} \end{array}$					0.06	0.12	MHz

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

* Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

§ Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND

¶ This parameter is derived for use in total power-supply calculations.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITION	CY	54FCT16	3Т	CY	74FCT16	3T		
PARAMETER		TEST CONDITION	12	MIN	TYP†	MAX	MIN	түр†	MAX	UNIT
	V _{CC} = 5.5 V, Load mode,	One bit switching at f ₁ = 5 MHz at	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array} \end{array} \label{eq:VIN}$		0.7	1.4				
	f ₀ = 10 MHz,	50% duty cycle	V_{IN} = 3.4 V or GND		1.2	3.4				
	Outputs open, $\underline{CEP} = CET =$ $\overline{PE} = GND$,	Four bits switching at	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array} \end{array} \label{eq:VIN}$		1.6	3.2				
۱ _C #	$\overline{SR} = V_{CC}$	f ₁ = 5 MHz at 50% duty cycle	V_{IN} = 3.4 V or GND		2.9	8.2				~ ^
IC.	$V_{CC} = 5.25 V,$ f ₀ = 10 MHz,	One bit switching at f ₁ = 5 MHz at	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array} \end{array} \label{eq:VIN}$					0.7	1.4	mA
	Load mode,	50% duty cycle	V_{IN} = 3.4 V or GND					1.2	3.4	
	Outputs open, $\underline{CEP} = CET =$ $\overline{PE} = GND$,	Four bits switching at f ₁ = 5 MHz at	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array} \end{array} \label{eq:VIN}$					1.6	3.2	
	$\overline{SR} = V_{CC}$	50% duty cycle	V_{IN} = 3.4 V or GND					2.9	8.2	
Ci					5	10		5	10	pF
Co					9	12		9	12	pF

[†] Typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

 ${}^{\#}I_{C} = I_{CC} + \Delta I_{CC} \times D_{H} \times N_{T} + I_{CCD} (f_{0}/2 + f_{1} \times N_{1})$

Where:

I_C = Total supply current I_{CC} = Power-supply current with CMOS input levels

 ΔI_{CC} = Power-supply current for a TTL high input (VIN = 3.4 V)

 D_H = Duty cycle for TTL inputs high

NT = Number of TTL inputs at DH

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

= Clock frequency for registered devices, otherwise zero fo

= Input signal frequency f1

N₁ = Number of inputs changing at f1

All currents are in milliamperes and all frequencies are in megahertz.

I Values for these conditions are examples of the I_{CC} formula.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			CY54FC	T163T	CY74FC1	163CT	UNIT
			MIN	MAX	MIN	MAX	UNIT
	Dulas duration high or law	Clock (load)	5		4		
tw	Pulse duration, high or low	Clock (count)	8		5		ns
		P before CP↑	5.5		3.5		
t _{su}	Setup time, high or low	PE or SR before CP↑	13.5		7.6		ns
		CEP or CET before CP↑	13		7.6		
		P after CP↑	2		1.5		
t _h	Hold time, high or low	PE or SR after CP↑	1.5		1		ns
		CEP or CET after CP↑	0		0		



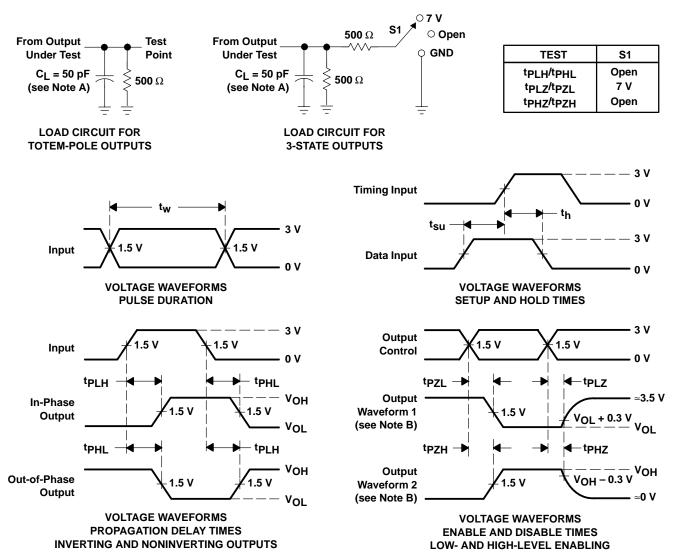
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switching characteristics over operating free-air temperature range (see Figure 1)

	PARAMETER	FROM	то	CY54FC	T163T	CY74FC1	UNIT	
	FARAINETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
^t PLH	Propagation delay	СР	Q	2	11.5	1.5	5.8	ns
^t PHL	(PE high)	GF	Q	2	11.5	1.5	5.8	115
^t PLH	Propagation delay	СР	тс	2	10	1.5	5.2	ns
^t PHL	(PE low)	GF	10	2	10	1.5	5.2	115
^t PLH		СР	тс	2	16.5	1.5	7.8	ns
^t PHL		CP	10	2	16.5	1.5	7.8	115
^t PLH		CET	тс	1.5	9	1.5	4.4	ns
^t PHL		GET	10	1.5	9	1.5	4.4	115



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_I includes probe and jig capacitance.

 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
CY54FCT163TLMB	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CY54FCT 163TLMB	Samples
CY74FCT163CTQCT	ACTIVE	SSOP	DBQ	16	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FT163-3	Samples
CY74FCT163CTSOC	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT163C	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

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⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT163CTQCT	SSOP	DBQ	16	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1



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PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT163CTQCT	SSOP	DBQ	16	2500	340.5	338.1	20.6



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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
CY54FCT163TLMB	FK	LCCC	20	1	506.98	12.06	2030	NA
CY74FCT163CTSOC	DW	SOIC	16	40	506.98	12.7	4826	6.6

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